

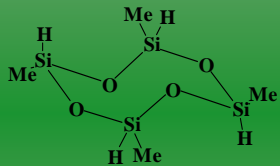
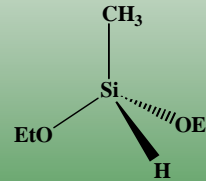
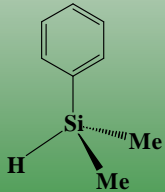
Supporting You at 45nm and Beyond

FFEM Thin Film Systems offers OEM qualified Ultra-Low K precursors and chemical delivery systems, including:

45nm Low K Chemistries:

Diethoxymethylsilane (M-DEOS™)
alpha-terpinene (aTER™)

BHDIII™



Other Advanced Processes:

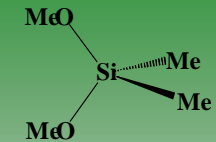
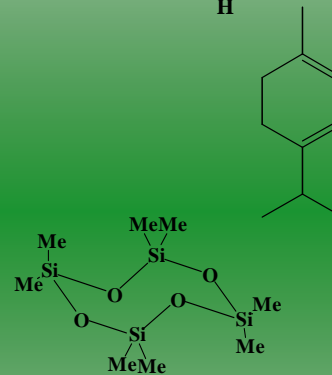
OMCTS

DMPS

TMSA

DMDMOS

32nm PECVD Siloxanes and Porogens



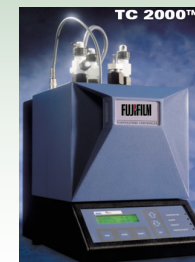
The GenStream® premier delivery system offers a seamless interface to bring our customers a total System SolutionSM.

- » Engineered to safely handle bulk pyrophorics
- » Patented venturi purge eliminates troublesome vacuum pumps
- » High MTBF and a strong return on investment

Delivery Equipment

GenStream® Liquid Chemical Delivery Systems

Temperature Controllers (TC-2000)



Good News For 45nm Low K!

FUJIFILM ELECTRONIC MATERIALS AND AIR PRODUCTS SIGN SOLE LICENSE AGREEMENT FOR PDEMS™ ILD PROCESS

North Kingston, RI, July 17, 2007 -- FUJIFILM Electronic Materials U.S.A., Inc. and Air Products (NYSE:APD) today announced that they have signed a sole, international licensing agreement for Air Products' patented PDEMS™ interlayer dielectric (ILD) Process. The technology is designed to make a porous low-k dielectric material by plasma-enhanced chemical vapor deposition (PECVD).

Fujifilm is a leading global supplier of low k precursor chemistries and thin film chemistry delivery systems. The license agreement enables Fujifilm to globally supply the materials to semiconductor manufacturers that make use of Air Products' patented PDEMS™ ILD Process. The PDEMS™ ILD Process, as developed by Air Products, is claimed in US Patent numbers 6,583,048 and 6,846,515. The chemistry will be available through FUJIFILM Electronic Materials affiliates around the world.

FUJIFILM Electronic Materials will sell its own M-DEOS™ (diethoxymethylsilane) and porogens for use in the PDEMS™ ILD Process. Both companies will interface directly with customers in selling their own manufactured precursors to be used in the patented process.

"Fujifilm is committed to partnering with our customers to ensure that they have the enabling materials and processes they need to foster greater innovation," said Keiji Miyahashi, President and CEO of FUJIFILM Electronic Materials U.S.A., Inc. "In addition to our existing broad product lines already supporting the semiconductor manufacturing and electronic materials markets, this license will allow for a new level of collaboration with our customers and OEM partners."

"Our customers have challenged material suppliers to step up and help them continue the historical rate of roadmap progress. The creation of Air Products' PDEMS™ ILD Process is a response to this challenge," said Corning Painter, Vice President of Electronics, for Air Products. "Our agreement with Fujifilm is a commitment by Air Products and Fujifilm to provide semiconductor manufacturers the ability to easily access this material technology anywhere in the world."

Highlights of this News Release:

- » **FFEM Signed a Sole, Worldwide License for the PDEMS™ Process Widely Used in 45nm Processing**
- » **Process Precursors include: Diethoxymethylsilane (M-DEOS™), alpha-terpinene (aTER™) and BHDIII™**
- » **FFEM is Free to Supply Precursors for Licensed Processes to Semiconductor Manufacturers Worldwide**
- » **Customers Who Purchase FFEM Licensed Products are Free to Practice the Licensed Processes**
- » **Using FFEM Supplied, OEM Qualified Products for 45nm are Now Even More Worry Free**